

54/74ETL16245 16-Bit Data Transceiver with Incident Wave Switching

General Description

The 54/74ETL16245 contains sixteen non-inverting bidirectional buffers with TRI-STATE® outputs designed with incident wave switching, live insertion support and enhanced noise margin for TTL backplane applications.

Both the A and B ports include a bus hold circuit to latch the output to the value last forced on that pin.

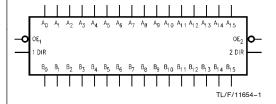
The B port of this device includes 25Ω series output resistors, which minimize undershoot and ringing.

Features

- Supports the VME64 ETL specification
- Functionally and pin compatible with industry standard TTL 16245 SSOP pinout

- Improved TTL-compatible input threshold range
- \blacksquare High drive TTL-compatible outputs (I_{OH} = -60 mA, I_{OL} = 90 mA)
- Supports 25Ω incident wave switching on the A port
- BiCMOS design significantly reduces power dissipation.
- \blacksquare Distributed V_{CC} and GND pin configuration minimizes high-speed switching noise
- \blacksquare 25 $\!\Omega$ series-dampening resistor on B-port
- Available in 48-pin SSOP and ceramic flatpak
- Guaranteed output skew
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Guaranteed latchup protection

Logic Symbol

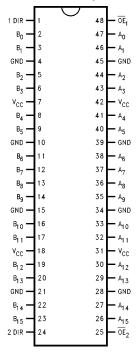


Pin Description

Pin Names	Description
DIR	Transmit/Receive Input
ŌĒ	Output Enable Input (Active LOW)
An	Backplane Bus Data
B _n	Local Bus Data

Connection Diagram

Pin Assignment for SSOP and Flatpak



TL/F/11654-2

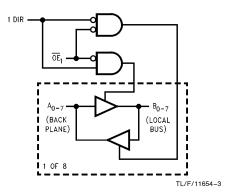
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Functional Description

The device uses byte-wide Direction (DIR) control and Output Enable (\overline{OE}) controls. The DIR inputs determine the direction of data flow through the device. The \overline{OE} inputs disable the A and the B ports.

The part contains active circuitry which keeps all outputs disabled when $\rm V_{CC}$ is less than 2.2V to aid in live insertion applications.

Logic Diagrams (Positive Logic)

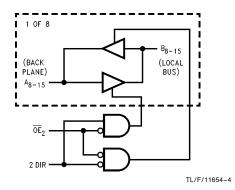


ETL's Improved Noise Immunity

TTL input thresholds are typically determined by temperature-dependent junction voltages which result in worst case input thresholds between 0.8V and 2.0V. By contrast, ETL provides greater noise immunity because its input thresholds are determined by current mode input circuits similar to those used for ECL or BTL. ETL's worst case input thresholds, between 1.4V and 1.6V, are compensated for temperature, voltage and process variations.

Truth Table (Each 8-bit Section)

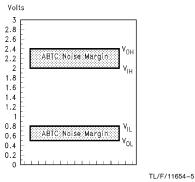
Inp	outs	Operation
ŌĒ	DIR	Operation
L	L	A Data to B Bus
L	Н	B Data to A Bus
Н	X	Isolation



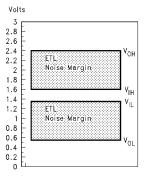
Incident Wave Switching

When TTL logic is used to drive fully loaded backplanes, the combination of low backplane bus characteristic impedance, wide TTL input threshold range and limited TTL drive generally require multiple waveform reflections before a valid signal can be received across the backplane. The VME International Trade Association (VITA) defined ETL to provide incident wave switching which increases the data transfer rate of a VME backplane and extends the life of VME applications. TTL compatibility with existing VME backplanes and modules was maintained.

Improved Input Threshold Characteristics of ETL



ABTC Worst Case V_{OUT}-V_{IN}



ETL Worst Case V_{OUT}-V_{IN}

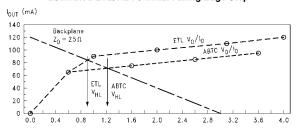
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Incident Wave Switching (Continued)

To demonstrate the incident wave switching capability, consider a VME application. A VME bus must be terminated to $+2.94\mathrm{V}$ with 190Ω at each end of its 21 card backplane. The surge impedance presented by a fully loaded VME backplane is approximately $25\Omega.$ If the output voltage/current of an ABTC driver is plotted with this load, the inter-

section at 1.2V for a falling edge and at 1.6V for a rising edge does not reach the worst case input threshold of a second ABTC circuit. This is shown in the two figures below. However, an ETL driver located at one end of the backplane is able to provide incident wave switching because it has a higher drive and a tighter input threshold.

Estimated ETL/ABTC Initial Falling Edge Step

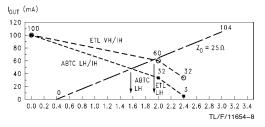


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TL/F/11654-9

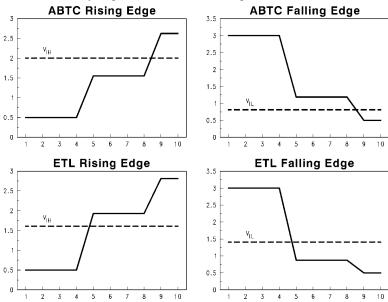
Because ETL has a much more precise input threshold region, an ETL receiver will interpret its predicted falling input of 0.85V as a logic ZERO and the initial rising edge of 1.9V as a logic ONE. This comparison is for the case of a 25Ω surge impedance backplane driven from one end.

Estimated ETL/ABTC Initial Rising Edge Step



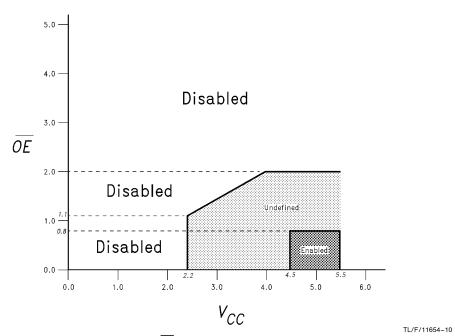
The resulting ABTC and ETL waveform predictions and their input thresholds are compared below. This shows how ETL can achieve backplane speeds not always possible with conventional TTL compatible logic families.

Comparing the Incident Wave Switching of ETL with ABTC





The figure V_{CC} Power-up Critical Voltages shows the relationship between \overline{OE} and V_{CC} while power is being applied and removed.



 V_{CC} and \overline{OE} Power-up Relationship

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature -65°C to +150°C -55°C to +125°C Ambient Temperature under Bias Junction Temperature under Bias

Ceramic -55°C to +175°C Plastic −55°C to +150°C

V_{CC} Pin Potential to Ground Pin

-0.5V to +7.0VInput Voltage (Note 2) -0.5V to +7.0VInput Current (Note 2) -50~mA to +5.0~mA

Voltage Applied to Any Output

in the Disabled or Power-off State in the HIGH State

Current Applied to Output in LOW State (Max)

DC Latchup Source Current -500 mA Over Voltage Latchup (I/O) 10V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature

-55°C to +125°C -40°C to +85°C Military Commercial Supply Voltage Military Commercial $+\,4.5V$ to $+\,5.5V$

 $+\,4.5V$ to $+\,5.5V$ (Δt/ΔV) 20 ns/V Minimum Input Edge Rate Data Input Enable Input 50 ns/V

DC Electrical Characteristics

Symbol	Parameter			15	Units	v _{cc}	Conditions	
Syllibol	Parameter		Min	Тур	Max	Ullits	VCC.	Conditions
V _{IH}	Input HIGH Voltage	ŌĒ	2.0			V		Recognized HIGH Signal
		Other Inputs	1.6			•		
V _{IL}	Input LOW Voltage	ŌĒ			0.8	V		Recognized LOW Signal
		Other Inputs			1.4	•		
V _{CD}	Input Clamp Diode Voltage				-1.2	>	Min	$I_{IN} = -18 \text{ mA } (\overline{OE}_{n}, DIR)$
V _{OH}	Output HIGH Voltage	B Port	2.4 2.0		V _{CC} - 1	V V V	Min	$I_{OH} = -100 \mu A$ $I_{OH} = -1 mA$ $I_{OH} = -12 mA$
		A Port	2.4 2.0		V _{CC} - 1	V V	Min	$I_{OH} = -1 \text{ mA}$ $I_{OH} = -32 \text{ mA}$ $I_{OH} = -60 \text{ mA}$
V _{OL}	Output LOW Voltage	B Port			0.4 0.8	V V	Min	$I_{OL} = 1 \text{ mA}$ $I_{OL} = 12 \text{ mA}$
		A Port			0.55 0.9	V V	Min	I _{OL} = 64 mA I _{OL} = 90 mA
I _{HOLD}	Bus Hold Current	A Port,	100			μΑ	Min	$\overline{OE} = HIGH,$ $V_O = 0.8V$
		B Port	-100			μΑ	IVIIII	$\overline{OE} = HIGH,$ $V_O = 2.0V$
l _{OFF}	Output Current, Power Down				100	μΑ	0.0	V_{CC} Bias = 0V V_{I} or $V_{O} \le 4.5$ V
II	Input Current Control Pins	54ETL			± 10	μΑ	5.5	$V_{IN} = 0$ or V_{CC}
	74ETL				±5	μΑ	5.5	V _{IN} = 0 or V _{CC}
I _{IH} + Iozh	Output Leakage Current				50	μΑ	5.5	$V_{OUT} = 2.7V, \overline{OE} = 2.0V$
I _{IL} +	Output Leakage Current				-50	μΑ	5.5	$V_{OUT} = 0.5V, \overline{OE} = 2.0V$

 $-0.5\mbox{V}$ to $5.5\mbox{V}$

 $-0.5\mbox{V}$ to $\mbox{V}_{\mbox{CC}}$

128 mA

DC Electrical Characteristics (Continued)

Cumbal	B	ETL16245			Heite	.,	0	
Symbol	Parameter	Min	Тур	Max	Units	V _{CC}	Conditions	
Іссн	Power Supply Current			40	mA	Max	All Outputs HIGH, $\overline{\text{OE}} = \text{LOW}, \text{DIR} = \text{HIGH or LOW}$	
ICCL	Power Supply Current			80	mA	Max	All Outputs LOW, $\overline{\text{OE}} = \text{LOW, DIR} = \text{HIGH or LOW}$	
Iccz	Power Supply Current			40	mA	Max	OE = HIGH All Others at V _{CC} or GND DIR = HIGH or LOW	
I _{CCD}	Dynamic I _{CC} No Load (Note 1)			0.15	mA/ MHz	Max	$\label{eq:decomposition} \begin{split} & \text{Outputs Open} \\ & \overline{\text{OE}}_{n} = \text{GND, DIR} = \text{HIGH} \\ & \text{One Bit Toggling, 50\% Duty Cycle} \end{split}$	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}			1.0	٧	5.0	$T_A = 25^{\circ}\text{C (Note 2)}$ $C_L = 50 \text{ pF; } R_L = 500\Omega$	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-1.4			V	5.0	$T_A = 25^{\circ}\text{C (Note 2)}$ $C_L = 50 \text{ pF; } R_L = 500\Omega$	
V _{OHV}	Minimum High Level Dynamic Output Voltage (Note 1)		2.7		V	5.0	$T_A = 25^{\circ}\text{C (Note 4)}$ $C_L = 50 \text{ pF; } R_L = 500\Omega$	
V _{IHD}	Minimum High Level Dynamic Input Voltage (Note 1)	2.0	1.5		V	5.0	$T_A = 25^{\circ}\text{C (Note 3)}$ $C_L = 50 \text{ pF; } R_L = 500\Omega$	
V _{ILD}	Maximum Low Level Dynamic Input Voltage (Note 1)		1.2	0.8	V	5.0	$T_A = 25^{\circ}\text{C (Note 3)}$ $C_L = 50 \text{ pF; } R_L = 500\Omega$	

Note 1: Guaranteed, but not tested.

 $\textbf{Note 2:} \ \text{Max. number of outputs defined as (n). n} - 1 \ \text{data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.}$

Note 3: Max. number of data inputs (n) switching. n-1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}). Guaranteed, but not tested.

Note 4: Max. number of outputs defined as (n). n - 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.

AC Electrical Characteristics

		74ETL		54E	TL	74ETL				
Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5V$		$T_{A}=-55^{\circ}\text{C to}+125^{\circ}\text{C} \ V_{CC}=4.5\text{V}-5.5\text{V}$		$T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$		Units	Fig. No.	
		Min	Тур	Max	Min	Max	Min	Max		
t _{PLH}	Propagation Delay A _n to B _n	1.5 1.5		7.0 7.0			1.5 1.5	7.0 7.0	ns	1, 2, 4
t _{PLH}	Propagation Delay B _n to A _n	1.5 1.5		7.0 7.0			1.5 1.5	7.0 7.0	ns	1, 2, 4
t _{PZH}	Output Enable Time	1.0 1.0		7.0 7.0			1.0 1.0	7.0 7.0	ns	1, 2, 3
t _{PHZ}	Output Disable Time	1.0 1.0		7.0 7.0			1.0 1.0	7.0 7.0	ns	1, 2, 3
t _r	Rise Time 1V \rightarrow 2V, A _n Outputs	1.2		3.0			1.2	3.0	ns	1, 2, 4
t _f	Fall Time 2V \rightarrow 1V, A _n Outputs	1.2		3.0			1.2	3.0	ns	1, 2, 4

Skew

••						
		74ETL	54ETL			
Symbol	Parameter	$T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ 16 Outputs Switching	T _A = -55°C to + 125°C V _{CC} = 4.5V-5.5V 16 Outputs Switching	Units	Conditions	
t _{OHS} (Notes 1, 2)	Pin-to-Pin Skew LH/HL An to Bn	1.3		ns	Figures 1, 2, 4	
t _{OHS} (Notes 1, 2)	Pin-to-Pin Skew LH/HL Bn to An	1.3		ns	Figures 1, 2, 4	
t _{PS} (Notes 1, 2)	Duty Cycle Skew Bn to An	2.0		ns	Figures 1, 2, 4	
t _{PS} (Notes 1, 2)	Duty Cycle Skew An to Bn	2.0		ns	Figures 1, 2, 4	

VME Extended Skew

		74ETL	54ETL		Conditions	
Symbol	Parameter	$ \begin{aligned} \mathbf{T_A} &= -40^{\circ} \mathbf{C} \text{ to } + 85^{\circ} \mathbf{C} \\ \mathbf{V_{CC}} &= 4.5 \text{V} - 5.5 \text{V} \\ 16 \text{ Outputs Switching} \end{aligned} $	$T_{A} = -55^{\circ}\text{C to} + 125^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ 16 Outputs Switching	Units		
		Max	Max			
t _{PV} (Notes 1, 2)	Device-to-Device Skew LH/HL Transitions Bn to An	4.0		ns	Figures 1, 2, 4	
t _{CP} (Notes 1, 2)	Device-to-Device Skew LH/HL Transitions An to Bn	2.5		ns	Figures 1, 2, 4	
t _{CP} (Note 1, 3)	Change in Propagation Delay with Load Bn to An	4.0		ns	Figures 1, 2, 4	
t _{CPV} (Notes 1, 2, 3)	Device-to-Device, Change in Propagation Delay with with Load Bn to An	6.0		ns	Figures 1, 2, 4	

Note 1: Skew is defined as the absolute difference in delay between two outputs. The specification applies to any outputs switching HIGH to LOW, LOW to HIGH, or any combination switching HIGH-to-LOW or LOW-to-HIGH. This specification is guaranteed but not tested.

Note 2: This is measured with both devices at the same value of V_{CC} $\pm 1\%$ and with package temperature differences of 20°C from each other.

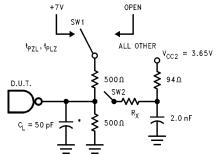
Note 3: This is measured with Rx in Figure 1 at 13Ω for one unit and at 56Ω for the other unit.

Capacitance

Symbol Parameter		Тур	Max	Units	Conditions, T _A = 25°C
C _{IN}	Input Capacitance	5	8	pF	$V_{CC} = 0.0V (\overline{OE}_n, DIR)$
C _{I/O} (Note 1)	Output Capacitance	9	12	pF	$V_{CC} = 5.0V (A_n)$

Note 1: $C_{I/O}$ is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012.

AC Loading



*Includes iig and probe capacitance

TL/F/11654-11

FIGURE 1. Standard AC Test Load

Note 1: Defined to emulate the range of VME bus transmission line loading as a function of board population and driver location. Rx = 13Ω , 26Ω or 56Ω depending on test.

Test	Test Port		SW2	Rx
t _{PHZ,}	A, B	+7	Open	
t _{PZH} , t _{PZL}	A, B	+7	Open	
t _{PLH} , t _{PHL}	А	Open	Closed	26
t _{PLH} , t _{PHL}	В	Open	Open	
t _r , t _f	Α	Open	Closed	26
t _{PV}	Α	Open	Closed	26
t _{CP}	В	Open	Open	
t _{CP}	Α	Open	Closed	13 then 56
t _{CPV}	Α	Open	Closed	13 and 56

FIGURE 1a

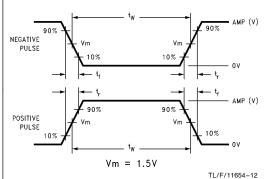


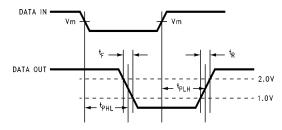
FIGURE 2. Input Pulse Requirements

ŌĒ	▼ Vm = 1.5V
	t _{PHZ}
DATA OUT	V _m V _{oh} V _{oh} 0.3v
	t _{PZL} t _{PLZ}
DATA OUT	Vm 0.3V V _{OL}
	TL/F/11654-13

FIGURE 3. TRI-STATE Output HIGH and LOW Enable and Disable Times

	Amplitude	Rep. Rate	t _w	t _r	t _f
ſ	3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 2a. Test Input Signal Requirements

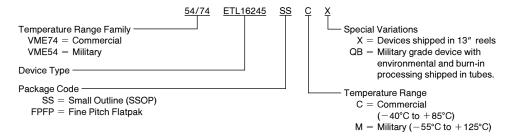


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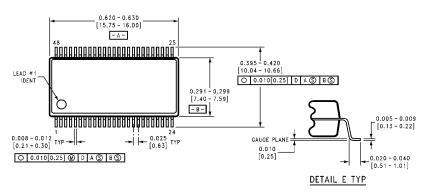
FIGURE 4. Rise, Fall Time and Propagation Delay Waveforms

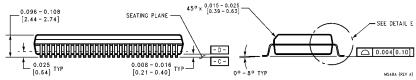
Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



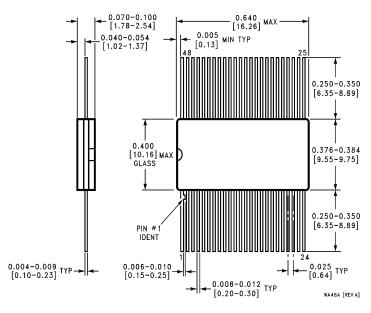
Physical Dimensions inches (millimeters)





48-Lead SSOP (0.300" Wide) (SS) NS Package Number MS48A

Physical Dimensions inches (millimeters) (Continued)



48-Pin Ceramic Flatpak (FPFP) **NS Package Number WA48A**

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National Semiconductor National Semiconducto Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018

National Semiconductor Europe

Fax: (+49) 0-180-530 85 86 Fax: (+49) U-18U-35U oo oo Email: onjwge@tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tel: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80 **National Semiconductor** Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960

National Semiconductor Japan Ltd.
Tel: 81-043-299-2309
Fax: 81-043-299-2408